

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: Product Affec	of all Logic de		MEANS OF DISTIN Product Mark Back Mark Date Code Other	GUISHING CHANG	ED DEVICES:
Date Effective: October 19, 2001 Contact: Bimla Paul					
Title:	Q.A. Manager		Attachment::	Yes	□ No
Phone #:	(408) 654-6419		Attachinent	103	
Fax #:	(408) 492-8362		Samples: N/A		
E-mail:	bimla.paul@idt.com		Samples. N/A		
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DESCRIPTION AND PURPOSE OF CHANGE:					
 Die Techn Wafer Fab Assembly Equipmen Material Testing 	rication Process Process	To comply with the requirement of reflow temperature of +235°C +5/-0°C per PC/JEDEC J-STD-020A. Moisture sensivitiy level of all TSSOP 48 & 56 Logic levices will be changed from level 1 (Non-Moisture Sensitive) to level 3 Moisture Sensitive)			
 □ Manufacturing Site □ Data Sheet ■ Other Moisture sensitivity label per effective 10/19/2001 (See at effect			per IPC/JEDEC J-STD-033 will be applied to the dry pack. attachment # 1).		
RELIABILITY/QUALIFICATION SUMMARY: Moisture sensitivity level is changed from level 1 to level 3.					
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.					
Customer:			Approval for s	hipments prior to	effective date.
Name/Date:		E-N	Mail Address:		
Title:		Pho	one#/Fax#:		
CUSTOMER COMMENTS:					
IDT ACKNOWLEDGMENT OF RECEIPT:					
RECD. BY:			DATE:		_



Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN) ATTACHMENT # 1 - PCN #: L0110-04

Moisture Sensitivity Label for level 3

